

### **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### **Listing of Claims:**

Claim 1 (currently amended): A method of patterning a functional group onto a substrate, comprising the steps of: (a) applying a layer of protective material, soluble in a solvent in which the functional material is insoluble, to at least one major surface of said substrate; (b) removing areas of said layer to gain access to the substrate in well-defined regions; (c) depositing the functional material ~~at least onto the substrate in the well-defined regions in a conformal thin film;~~ and (d) removing the remaining layer of protective material from the substrate by dissolution in said solvent.

Claim 2 (original): A method of claim 1, wherein said substrate comprises glass.

Claim 3 (withdrawn): A method of claim 1, wherein said substrate comprises silicon.

Claim 4 (withdrawn): A method of claim 1, wherein said substrate comprises plastics material.

Claims 5-33 (canceled).

Claim 34 (previously presented): A method according to claim 1, wherein said substrate comprises a charge injection layer.

Claim 35 (previously presented): A method according to claim 1, wherein said protective material comprises organic material.

Claim 36 (previously presented): A method according to claim 35, wherein said layer of protective material comprises a water soluble polymer selected from poly(vinyl alcohol), polymethyl ether, polymethylacrylamide, doped polythiophene, polyethylene glycol, and doped polyaniline.

Claim 37 (withdrawn): A method according to claim 1, wherein said layer of protective material comprises an alcohol soluble polymer.

Claim 38 (withdrawn): A method according to claim 1, wherein said protective material comprises inorganic material.

Claim 39 (withdrawn): A method according to claim 38, wherein said protective material is selected from silicon, silicon nitride, and silicon oxide.

Claim 40 (previously presented): A method according to claim 1, wherein a layer of a second protective material is applied subsequent to step (a), is removed in the well-defined regions in step (b), and is subsequently removed other than in the well-defined regions.

Claim 41 (withdrawn): A method according to claim 40, wherein said layer of second protective material comprises an inorganic material.

Claim 42 (withdrawn): A method according to claim 41, wherein said layer of second protective material is selected from silicon, silicon nitride, and silicon oxide.

Claim 43 (previously presented): A method according to claim 40, wherein said layer of second protective material comprises a metal layer.

Claim 44 (previously presented): A method according to claim 43, wherein said layer of second protective material is selected from nickel, aluminum, and chromium.

Claim 45 (previously presented): A method according to claim 40, wherein, in step (b), said layer of second protective material is removed from the well-defined regions using a first process to expose said areas of said protective material, and wherein said areas of protective material are removed using a second process to gain access to the substrate.

Claim 46 (previously presented): A method according to claim 45, wherein said first process comprises laser ablation.

Claim 47 (withdrawn): A method according to claim 45, wherein said first process comprises a stamping or puncturing process.

Claim 48 (withdrawn): A method according to claim 45, wherein said first process comprises a photolithography step to define and expose said layer of second protective material in well-defined regions, and said second process comprises an etching step.

Claim 49 (previously presented): A method according to claim 1, wherein, in step (b), said protective material is removed from the well-defined regions by laser ablation.

Claim 50 (withdrawn): A method according to claim 1, wherein, in step (b), said protective material is removed from the well-defined regions using a lift off process.

Claim 51 (previously presented): A method according to claim 1, wherein, in step (c), the functional material is deposited by a method selected from spin coating, evaporation, and sputtering.

Claim 52 (previously presented): A method according to claim 1, wherein, in step (c), an additional layer of protective material is applied over the functional material, said additional layer being removed in step (d).

Claim 53 (previously presented): A method according to claim 52, wherein said additional layer comprises the same protective material, soluble in a solvent in which the functional material is insoluble.

Claim 54 (previously presented): A method according to claim 1, wherein said functional material comprises an organic electro-optically active material.

Claim 55 (withdrawn): A method according to claim 1, wherein said functional material comprises a biochemical or biological reagent.

Claim 56 (previously presented): A method according to claim 1, further comprising the steps of patterning a further functional material to the substrate, the further steps comprising repeating steps (a) to (d) for the further functional material.

Claim 57 (previously presented): A method according to claim 1, further comprising the steps, after step (c), of applying an additional layer of protective material; removing areas of said additional layer to gain access to the substrate in additional well-defined regions; and depositing an additional functional material at least onto the substrate in the additional well defined regions.

Claim 58 (canceled).